

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-181450

(43)Date of publication of application : 11.07.1997

(51)Int.CI.

H05K 3/46

(21)Application number : 07-340119

(71)Applicant : KYOCERA CORP

(22)Date of filing : 27.12.1995

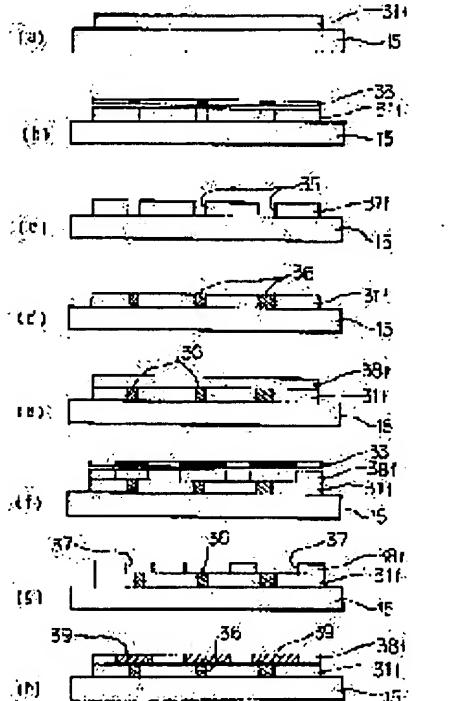
(72)Inventor : MATSUMOTO YUZURU
FUKAMIZU NORIMITSU
NAKAMIYA MICHINOBU
IMOTO AKIRA

(54) METHOD FOR MANUFACTURING MULTILAYER CERAMIC CIRCUIT BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To prevent an interlayer insulation fail by a method wherein a stacked formation body is formed with a penetrating groove of an internal wire pattern form in a specific location of a plurality of insulation layer forming body, and an insulation formation body for a pattern that conductive paste is filled in the penetrating groove is formed via something.

SOLUTION: A slip material is applied and dried on a support board 15 to form an insulation layer formation body 31f, and a penetrating hole is formed. Conductive paste is filled in a penetrating hole 35 and dried, and a conductive member 36 being a via hole conductor is formed. The slip material is applied to the insulation layer formation body 31f and dried, and an insulation layer formation body 38f for a pattern is formed. An internal wire pattern forming penetrating groove 37 is formed, and conductive paste is filled in the penetrating groove 37 to form an internal wire pattern 39 being an internal wire. Thus, The insulation layer formation body 38f for a pattern containing the internal wire pattern 39 and an insulation layer formation body 31 containing a via hole conductor 3 are formed, so that an interlayer insulation fail can be prevented.



LEGAL STATUS

[Date of request for examination] 16.02.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 3231987

[Date of registration] 14.09.2001

[Number of appeal against examiner's decision of
rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office